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IN THE CLAIMS

Please cancel Claims 16-23 without prejudice or disclaimer.

Please add the following new Claims:

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New Claim 24. A semiconductor assembly, comprising:

a leadframe;  
a die coupled to the leadframe;  
a mold compound for encapsulating the semiconductor assembly; and  
means formed in a top surface of the leadframe for forming a lock between the mold compound and the leadframe.

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New Claim 25. A semiconductor assembly in accordance with Claim 24 wherein said means formed in the top surface of the leadframe further is used for allowing the mold compound to flow into the means and bond with the means.

New Claim 26. The semiconductor assembly in accordance with Claim 24 further comprising:

a first raised area on the leadframe where the die is coupled; and

a plurality of second raised areas on the leadframe used for wirebonds wherein the plurality of second raised areas allow the mold compound to get underneath the wirebonds and capture the wirebonds.

New Claim 27. The semiconductor assembly in accordance with Claim 24 wherein the means is formed by stamping and coining the leadframe.

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concl.*

New Claim 28. The semiconductor assembly in accordance with Claim 24 wherein the means is formed by etching the leadframe.

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CLEAN VERSION OF NEW CLAIMS

Claim 24. A semiconductor assembly, comprising:

a leadframe;

a die coupled to the leadframe;

a mold compound for encapsulating the semiconductor assembly; and

means formed in a top surface of the leadframe for forming a lock between the mold compound and the leadframe.

Claim 25. A semiconductor assembly in accordance with Claim 24 wherein said means formed in the top surface of the leadframe further allows the mold compound to flow into the means and bond with the means.

Claim 26. The semiconductor assembly in accordance with Claim 24 further comprising:

a first raised area on the leadframe where the die is coupled; and

a plurality of second raised areas on the leadframe used for wirebonds wherein the plurality of second raised areas allow the mold compound to get underneath the wirebonds and capture the wirebonds.

Claim 27. The semiconductor assembly in accordance with Claim 24 wherein the means is formed by stamping and coining the leadframe.

Claim 28. The semiconductor assembly in accordance with Claim 24 wherein the means is formed by etching the leadframe.